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0.20

Ø 0.76 SOLDER BALLS

Ø 0.30 P M

450X
SEE NOTE 2

(0.55)

POS. A1
MARKER

OPTIONAL PICK-UP CAP

POS. A1

POS. A2

25.50

28.60

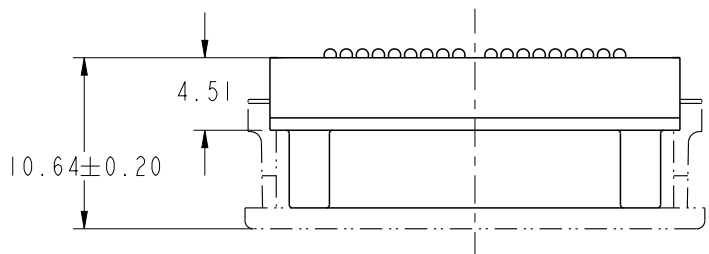
POS. T25

R1.25
4X

38.20±0.15

P

M



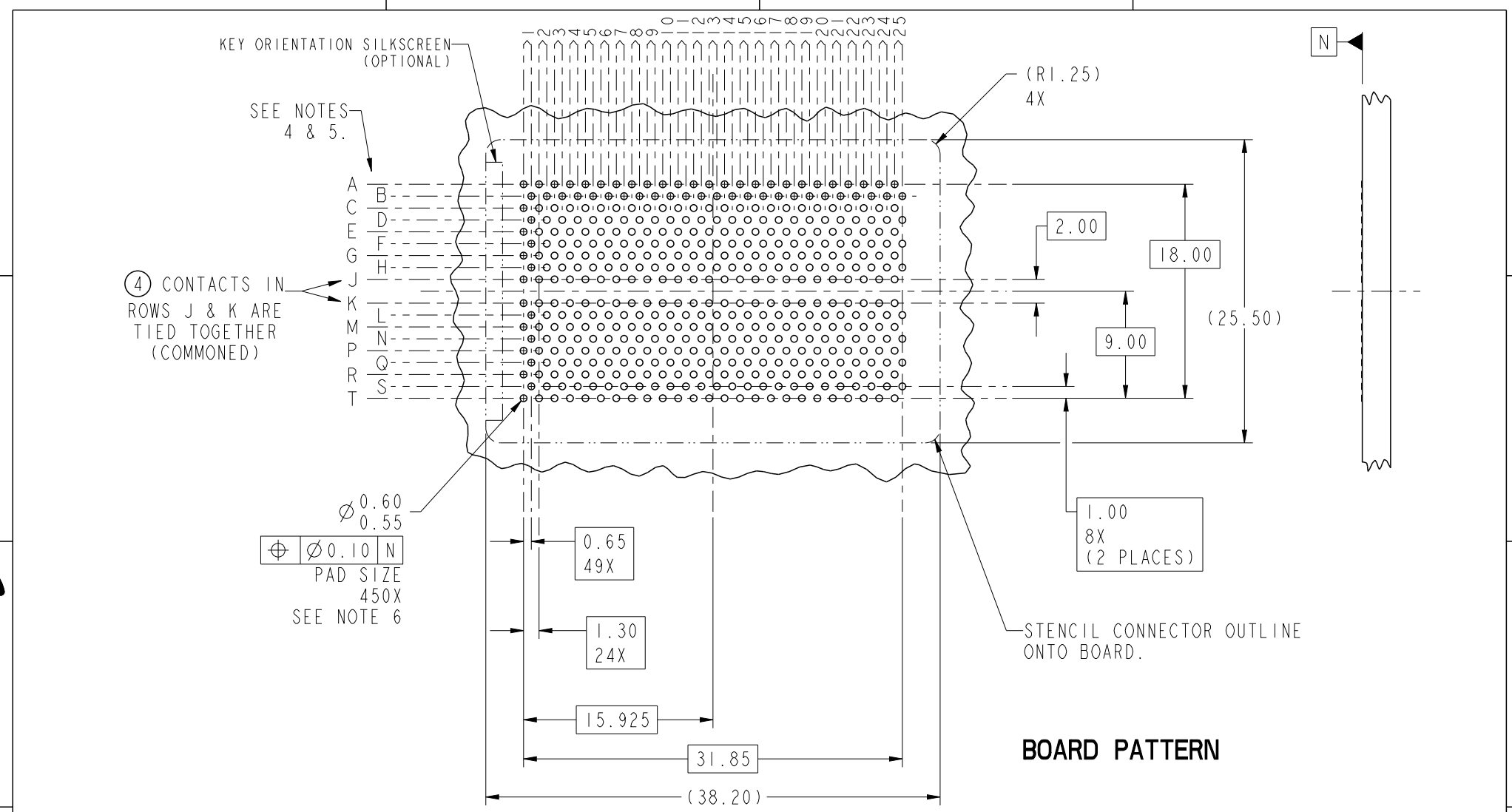
rev	ecn no	dr	date
A	V06-0001	DAI	2006-01-10
B	V06-0109	LP	2006-04-21
C	V06-0435	LP	2006-05-08
D	V06-0523	LP	2006-05-31
E	V06-0558	LP	2006-06-21
F	V08-0489	SM	2008-11-19

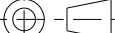
spec ref *				dr Bill Lin		2010/02/02		projection		mm		size A4		scale 11:10					
tolerance std ASME Y14.5 -		TOLERANCES UNLESS OTHERWISE SPECIFIED				eng Nickor Zuo		2011/06/09						ecn no ELX-DG-003943-1					
						chr Alex Cao		2011/06/24											
						appr Pei-Ming Zheng		2011/06/27						product family GIG-Array		rel level Released			
surface ✓ -		linear		0.X ±0.30		0.XX ±0.10		0.XXX ±0.05				title GIG-Array		5mm RECP. ASSY. 200 SIG. POS.		dwg no 55740		rev G	
		angular		0° ±2°		www.fci.com		cat. no. *		Product - Customer Drw		sheet 1 of 5							

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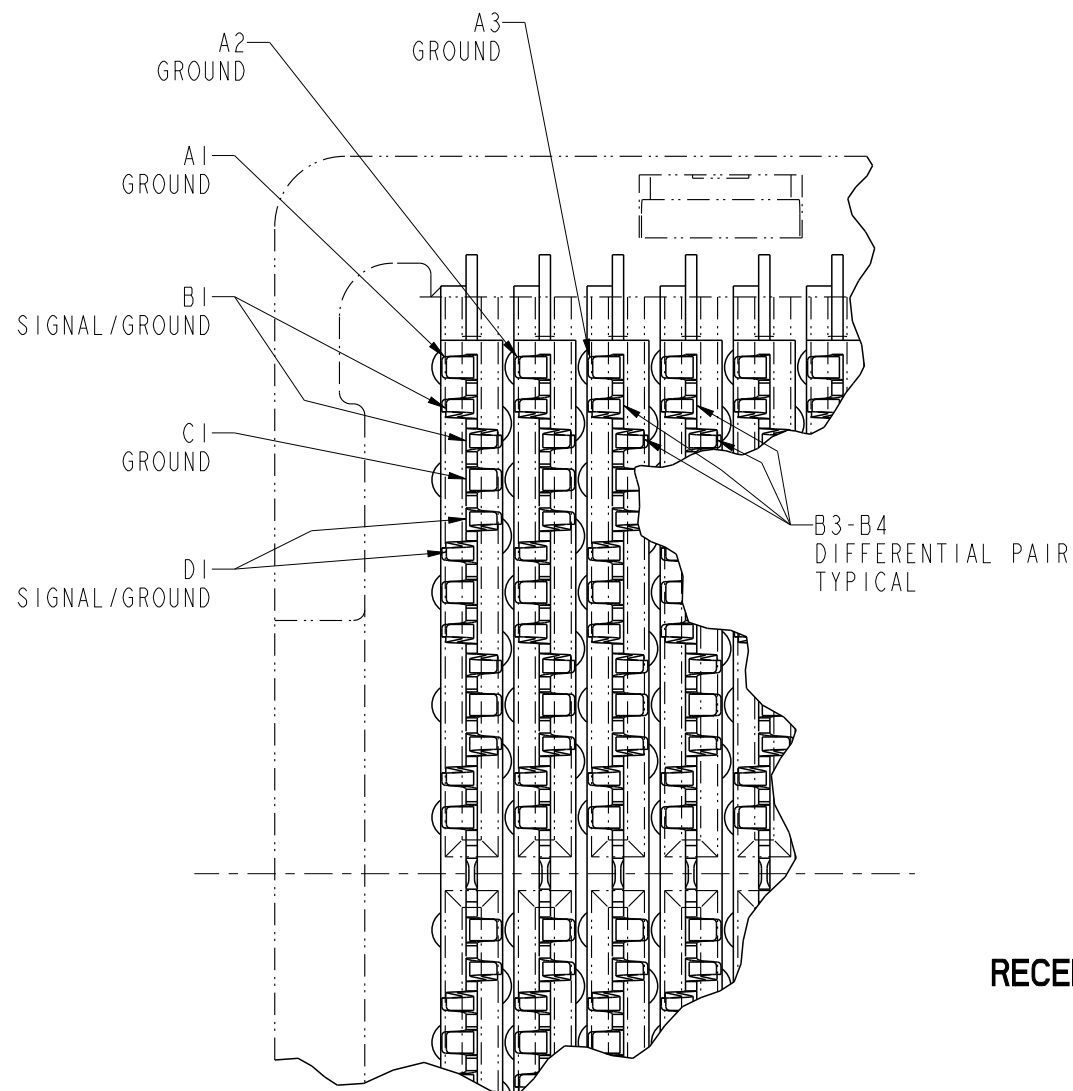


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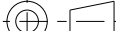


spec ref *				dr Bill Lin 2010/02/02		projection 	 mm	size A4	scale 11:10
tolerance std ASME Y14.5 -	TOLERANCES UNLESS OTHERWISE SPECIFIED			eng Nickor Zuo 2011/06/09				ecn no ELX-DG-003943-1	
				chr Alex Cao 2011/06/24				rel level Released	
				appr Pei-Ming Zheng 2011/06/27					
product family						GIG-Array			
surface ✓ -	linear	0.X	±0.30		title GIG-Array 5mm RECP. ASSY. 200 SIG. POS.	dwg no 55740	rev G		
		0.XX	±0.10						
		0.XXX	±0.05						
	angular	0°	±2°					www.fci.com	cat. no.

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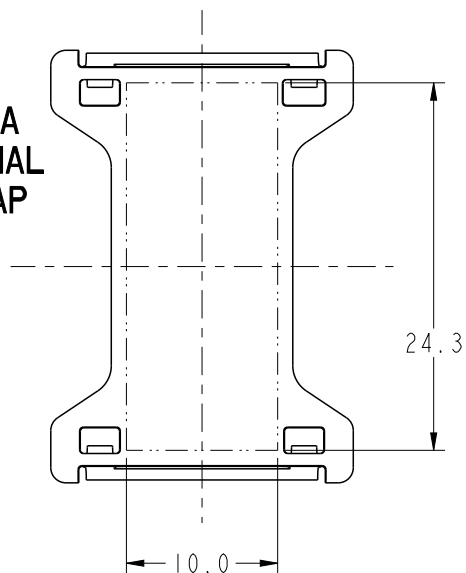


RECEPTACLE INTERFACE DESCRIPTION

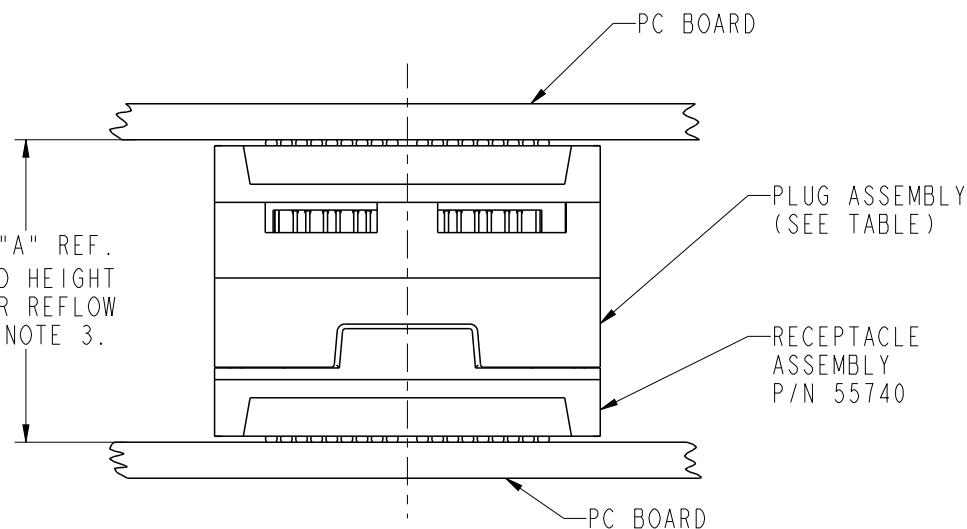
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tolerance std ASME Y14.5 -	TOLERANCES UNLESS OTHERWISE SPECIFIED			eng	Nickor Zuo	2011/06/09			ecn no	ELX-DG-003943-1		
				chr	Alex Cao	2011/06/24						
				appr	Pei-Ming Zheng	2011/06/27	product family		GIG-Array		rel level Released	
surface ✓ -	linear	0.X	±0.30		title GIG-Array 5mm RECP. ASSY. 200 SIG. POS.			dwg no 55740	rev G			
		0.XX	±0.10									
		0.XXX	±0.05									
	angular	0°	±2°	www.fci.com	cat. no.		*	Product - Customer Drw		sheet 3 of 5		

ProjE File - REV C - 2009-06-09

FLAT AREA
FOR OPTIONAL
PICK-UP CAP
SCALE 2:1

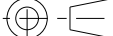


DIM "A" REF.
MATED HEIGHT
AFTER REFLOW
SEE NOTE 3.



END VIEW OF MATED CONNECTORS
SCALE 2:1

DIM. "A"	PLUG ASSEMBLY P/N
15	55737
17	10026802
18	10030626
20	55738
25	55739
30	10054783

spec ref *				dr Bill Lin2010/02/02		projection 	mm 	size A4	scale 11:10
tolerance std ASME Y14.5 -TOLERANCES UNLESS OTHERWISE SPECIFIED				eng Nickor Zuo2011/06/09				ecn no ELX-DG-003943-1	
				chr Alex Cao2011/06/24					
				appr Pei-Ming Zheng2011/06/27		product family GIG-Array		rel level Released	
surface ✓ -	linear	0.X	±0.30		title GIG-Array 5mm RECP. ASSY. 200 SIG. POS.		dwg no 55740	rev G	
		0.XX	±0.10						
		0.XXX	±0.05						
		angular	0°	±2°	www.fci.com	cat. no. *		Product - Customer Drw	



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PRODUCT NUMBER	SOLDER BALL COMPOSITION	CONTACT PLATING PERFORMANCE LEVEL
55740-001	STANDARD (EUTECTIC)	PERFORMANCE-BASED PLATING, QUALIFIED TO MEET THE REQUIREMENTS OF FCI PRODUCT SPECIFICATION GS-12-192, INCLUDING TELCORDIA CENTRAL OFFICE
55740-001LF	LEADFREE	
55740-201	STANDARD (EUTECTIC)	
55740-201LF	LEADFREE	

NOTES:

- ① MATERIAL:
HOUSING: LCP
CONTACT: COPPER ALLOY
PLATING (CONTACT): SEE TABLE.
UL RATING: 94 V-0
SOLDERBALL: (SEE TABLE) EUTECTIC
SnPb OR LEAD FREE 95.5 Sn/4Ag/0.5Cu.
- ② SOLDER BALLS WILL NOT BE PERFECT
SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③ MATED HEIGHT EFFECTED BY CUSTOMERS'
PCB PAD SIZE, PLATING, SOLDER REFLOW
PROFILE & SOLDER PASTE.
- ④ CONTACTS IN ROWS A,C,E,G,J,K,M,P,R AND T
ARE SINGLE BEAM CONTACTS,
TYPICALLY USED AS GROUND PINS.
(NOTE: CONTACTS IN ROWS J & K ARE
TIED TOGETHER [COMMONED])
- ⑤ CONTACTS IN ROWS B,D,F,H,L,N,Q AND S
ARE DUAL BEAM CONTACTS,
TYPICALLY USED AS SIGNAL PINS.

- ⑥ SPECIFIED POSITIONAL TOLERANCE DEFINES PAD TO PAD
LOCATION WITHIN LAND PATTERN. POSITIONAL TOLERANCE
OF LAND PATTERN TO FUDICIAL MARKS OR PCB DATUMS
SHALL BE DEFINED BY CUSTOMER. FOR RECOMMENDED
PRODUCT APPLICATION AND PCB DESIGN DETAILS, SEE
DOC. NO. GS-20-016.
- ⑦ FOR PROPER APPLICATION FOLLOW FCI APPLICATION
SPECIFICATION GS-20-033. LEAD FREE SOLDER BALLS WILL
NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS
DUE TO A HIGHER REFLOW TEMPERATURE. LEADFREE
PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE
WITH LEADED OR SOME SOLDERING APPLICATIONS.
REFERENCE FCI APPLICATION SPECIFICATION.
- ⑧ THIS PRODUCT MEETS THE EUROPEAN UNION
DIRECTIVES AND OTHER COUNTRY
REGULATIONS AS DESCRIBED IN GS-22-008.
PRODUCT MEETING THIS DIRECTIVE IS
IDENTIFIED IN THE CODE NUMBER
MARKED ON EACH PART BY HAVING
AN "X" IN THE SEVENTH CHARACTER
POSITION.

spec ref		*		dr		Bill Lin	2010/02/02	projection				size		A4	scale		11:10														
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED		eng		Nickor Zuo	2011/06/09					ecn no		ELX-DG-003943-1																	
ASME Y14.5				chr		Alex Cao	2011/06/24					rel level		Released																	
-				appr		Pei-Ming Zheng	2011/06/27					product family		GIG-Array																	
surface				linear		0.X		±0.30				title		GIG-Array		dwg no		55740		rev		G									
-		angular		0°		±2°		www.fci.com		cat. no.		*		Product - Customer Drw		sheet 5 of 5															

ProjE File - REV C - 2009-06-09

PDS: Rev :G

STATUS:Released

Printed: Jun 28, 2011